

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

3/19/02
Applicant : Detlef Weber Art Unit : Unknown
Serial No. : Not assigned yet Examiner : Unknown
Filed : Herewith
Title : METALLIZATION ARRANGEMENT FOR SEMICONDUCTOR STRUCTURE
AND CORRESPONDING FABRICATION METHOD

Commissioner for Patents
Washington, D.C. 20231

PRELIMINARY AMENDMENT

Prior to examination, please amend this application as follows:

In the specification:

On page 1, line 1, delete "Description"

On page 1, line 5, insert - **BACKGROUND--**

On page 2, line 24, insert --SUMMARY--

On page 2, delete the paragraph that begins on line 28

On page 3, line 6, delete the paragraph beginning on line 6

On page 4, line 18, insert **BRIEF DESCRIPTION OF THE FIGURES--**

44 On page 4, line 31, insert --DETAILED DESCRIPTION--

In the claims:

Please cancel claims 1-6 and claims 7-13

Please consider the following new claims 14-20 and 21-27

CERTIFICATE OF MAILING BY EXPRESS MAIL

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I hereby certify under 37 CFR §1.10 that this correspondence is being deposited with the United States Postal Service as Express Mail Post Office to Addressee with sufficient postage on the date indicated below and is addressed to the Commissioner for Patents, Washington, D.C. 20231.

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